

#### INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference 800186WO International application No. PCT/FI 03/00575		FOR FURTHER ACTION  See Notification of Transmittal of International Preliminary Examination Report (Form PCT/IPEA/416)			
		International filing date (day/n 18.07.2003	onth/year) Priority date 26.07.200	(day/month/year)	
	al Patent Classification (IPC) o	r both national classification and IP	>		
Applicant DETECT	ION TECHNOLOGY OY	et al.			
1. This	international preliminary e nority and is transmitted to	xamination report has been pre he applicant according to Artic	pared by this International Pre	liminary Examining	
2. This	REPORT consists of a tot	al of 5 sheets, including this co	ver sheet.		
⊠	been amended and are the (see Rule 70.16 and Sec	panied by ANNEXES, i.e. sheen basis for this report and/or stion 607 of the Administrative Ir	eets containing rectifications i	nd/or drawings which have made before this Authority	
The	se annexes consist of a tot	al of 4 sneets.			
			-	,	
3. This	report contains indications	relating to the following items:			
I	Basis of the opinior				
H	☐ Priority				
111	☐ Non-establishment	of opinion with regard to novelt	, inventive step and industrial	applicability	
IV	☐ Lack of unity of inve				
V	Reasoned statement citations and explan	nt under Rule 66.2(a)(ii) with re nations supporting such statem	ard to novelty, inventive step nt	or industrial applicability;	
VI	☐ Certain documents	·			
VII		ne international application			
VIII	☐ Certain observation	s on the international application	1		
		Do	of completion of this report		
Date of sub	emission of the demand	Dat	of completion of this report		
12.02.20	04	04	10.2004		
	mailing address of the internatexamining authority:	ional Aut	orized Officer	. Surviver of Patenteson, . C.	
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International application No.

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I.	Basi	s or	tne	rep	JOIL

1. With regard to the **elements** of the international application (Replacement sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to in this report as "originally filed" and are not annexed to this report since they do not contain amendments (Rules 70.16 and 70.17)):

	Des	cription, Pages	
	1-13	3	as originally filed
	Clai	ms, Numbers	
	1-39	9	received on 27.09.2004 with letter of 27.09.2004
	Dra	wings, Sheets	
	1-8		as originally filed
2.	With lang	n regard to the <b>langua</b> guage in which the inte	age, all the elements marked above were available or furnished to this Authority in the ernational application was filed, unless otherwise indicated under this item.
	The	se elements were ava	ailable or furnished to this Authority in the following language: , which is:
		the language of a tra	inslation furnished for the purposes of the international search (under Rule 23.1(b)).
		the language of publ	ication of the international application (under Rule 48.3(b)).
		the language of a tra Rule 55.2 and/or 55.3	nslation furnished for the purposes of international preliminary examination (under 3).
3.	With inte	h regard to any <b>nucle</b> rnational preliminary	otide and/or amino acid sequence disclosed in the international application, the examination was carried out on the basis of the sequence listing:
		contained in the inte	rnational application in written form.
		filed together with th	e international application in computer readable form.
		furnished subsequer	ntly to this Authority in written form.
		furnished subsequer	ntly to this Authority in computer readable form.
		in the international a	he subsequently furnished written sequence listing does not go beyond the disclosure application as filed has been furnished.
		The statement that t listing has been furn	he information recorded in computer readable form is identical to the written sequence ished.
4.	The	e amendments have r	esulted in the cancellation of:
		the description,	pages:
		the claims,	Nos.:
		the drawings,	sheets:

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5. L	]	This report has been established as if (some of) the amendments had not been made, since they have
		been considered to go beyond the disclosure as filed (Rule 70.2(c)).

(Any replacement sheet containing such amendments must be referred to under item 1 and annexed to this report.)

6. Additional observations, if necessary:

V. Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

1. Statement

Novelty (N)

Yes: Claims

No:

1-35

Inventive step (IS)

Yes: Claims

Claims

1-35

No: Claims

Industrial applicability (IA)

Yes: Claims

1-35

No: Claims

2. Citations and explanations

see separate sheet

- 1. Reference is made to the following documents:
  - D1: PATENT ABSTRACTS OF JAPAN vol. 1999, no. 14, 22 December 1999 (1999-12-22) & JP 11 261086 A (SHARP CORP), 24 September 1999
  - D2: WO 98 54554 A (HILSUM CYRIL ;SECR DEFENCE (GB); WATTON REX (GB)) 3 December 1998 (1998-12-03)
  - D3: US-A-5 599 744 (MCCAUSLAND CONNIE S ET AL) 4 February 1997
  - D4: US-B1-6 173 031 (KOTIAN FRANCOIS ET AL) 9 January 2001
  - D5: US-B1-6 396 898 (SAITO YASUO ET AL) 28 May 2002 (2002-05-28)
- 2. The Application does not meet the Requirements of Art.6 PCT because claims 1 & 20 are not clear.
- 2.1 The claims 1 & 20 feature "cathode on a second surface of the substrate" concerns a means of operating the device which thus does correspond to an unambiguously defined device feature. Moreover, support for the generalised cathode feature, not comprising an active area on the second surface of the substrate, cf. claim 13 as originally filed, essential to the invention since it provides a solution to the problem of the limitation on the size of photodetector arrays, cf. description pg.2, could not be located Art.6 as well as Art.34(2)(b) PCT.
- 2.2 The claims 1 & 20 feature "array of <u>photodetectors</u> for computed tomography" is unclear since it is not apparent if protection is sought only for the photodetector array as such (suitable for uses such as computed tomography) or if protection is sought for an array of photodiodes of a computed tomography system. Moreover, the available support for the first option could not be located, cf. claims 1,18-20 as originally filed, Art.6 as well as Art.34(2)(b) PCT.
- 3. Interpreting the claims with the aid of the description, cf. objections of Section 2 above, attention is drawn to the following:
- 3.1 D1, cf. Abs. & Fig.3 concerns a via connected photodiode array with active area connections on the substrate lower surface, used in a battery. There is no disclosure for an array of photodiodes of a computed tomography system
- 3.2 D2, cf. Abs.fig. concerns a photodetector array with one electrode via connected through an underlying substrate. There is no disclosure of a substrate with active regions on upper & lower surfaces.

### INTERNATIONAL PRELIMINARY

- **EXAMINATION REPORT SEPARATE SHEET**
- 3.3 D3, cf. Figs.1-6 & text discloses via substrates for photodetectors. There is no disclosure of a substrate with active regions on upper & lower surfaces.
- 3.4 D4, cf. fig.4 & text & D5, cf. fig.20 disclose photodiode arrays in CT systems. There are no details of the photodetector array devices.

The claimed subject-matter is therefore new. D1 is closest prior art however does not point to an array of such photodiodes of a computed tomography system. Consequently an inventive nature of claim 1 & corresponding method claim 20 is appreciated.

#### **CLAIMS**

- 1. A substrate including an array of photo-detectors, each photodetector of the array having an active area on a first surface of the substrate and a cathode on a second surface of the substrate, wherein each photodetector of the array is provided with a conductive via from the first surface of the substrate to the second surface of the substrate for connecting the active area to the second surface of the substrate.
- 2. A substrate according to claim 1 wherein the conductive vias are electrically isolated from the substrate.
- 10 3. A substrate according to claim 1 or claim 2 wherein the conductive vias comprise polysilicon.
  - 4. A substrate according to claim 3 wherein the polysilicon is formed on the inner walls of the vias.
- 5. A substrate according to claim 4 wherein there is provided a further conductive element from the first side of the substrate to the second within at least one of the conductive vias.
  - 6. A substrate according to claim 4 wherein there is provided a filling material within at least one of the conductive vias.
- A substrate according to any one of claims 1 to 6 wherein there is provided
   a further conductive element connected between the active area of the at least one of the photo-detectors and the respective conductive via.
  - 8. A substrate according to any one of claims 1 to 7 wherein there is provided a further conductive element on the second side of the substrate connected to at least one of the conductive vias.
- 25 9. A substrate according to claim 8 wherein the further conductive element on the second side of the substrate is for making an off-chip connection to the conductive via.
  - 10. A substrate according to any one of claims 1 to 9 wherein the photodetectors are photodiodes

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- 11. A substrate according to claim 10 wherein the active areas on the first surface of the substrate anodes.
- 12. A substrate according to any one of claims 1 to 11 wherein the cathodes of the photo-detectors are formed as a layer on the second surface.
- 5 13. A substrate according to any one of claims 1 to 12 wherein the photodetectors are photodiodes of a medical imaging system.
  - 14. A substrate according to claim 13 wherein the medical imaging system is a computed tomography system.
- 15. A substrate according to any one of claims 1 to 14 wherein the array of photo-detectors extends in two directions.
  - 16. A substrate according to any one of claims 1 to 15 wherein the array of photo-detectors is arranged into a plurality of sub-arrays of photo-detectors.
  - 17. A substrate according to any one of claims 1 to 16, wherein the vias are adjacent to the respective photo-detectors.
- 15 18. An imaging system comprising: a radiation detector including a photodetector array formed in at least one substrate according to any one of claims 1 to 17, a radiation source facing the radiation detector, and means for controlling the radiation detector and the radiation source.
- 19. An imaging system according to claim 18 wherein the radiation source is 20. an X-ray tube equipped with a high-voltage generator.
  - 20. An imaging system according to claim 18 or claim 19 wherein the radiation detector and the radiation source are radially mounted in a cylindrical scanning structure.
- 21. An imaging system according to any one of claims 18 to 20 wherein the means for controlling comprises a computer system.
  - 22. A method of manufacturing an array of photo-detectors comprising: providing for each of the photodetectors of the array an active area on a first surface of a substrate; providing for each of the photo-detectors a cathode on a second surface of the substrate; forming for each of the photo-detectors a conductive via through the substrate from the first surface of the substrate to a

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second surface of the substrate, the conductive via being adjacent to the respective anode; and connecting the active areas to the conductive vias such that the active areas are connected to the second surface of the substrate.

- A method according to claim 22 further comprising the step of electrically 23. isolating the conductive vias from the substrate.
  - A method according to claim 22 or claim 23 wherein the conductive vias comprise polysilicon.
  - A method according to claim 24 further comprising the step of forming polysilicon on the inner walls of the vias.
- A method according to claim 25 further comprising the step of providing at 10 least one further conductive element from the first surface of the substrate to the second surface within at least one of the conductive vias.
  - 27. A method according to claim 25 further comprising the step of providing a filling material within at least one of the conductive vias.
- A method according to any one of claims 22 to 27 further comprising the 15 28. step of providing at least one further conductive element connected between at least one of the active areas and at least one of the conductive vias.
- A method according to any one of claims 22 to 28 further comprising the 29. step of providing at least one further conductive element on the second surface of the substrate connected to at least one of the conductive vias. 20
  - A method according to claim 28 wherein the further conductive element is 30\_ a contact pad.
  - A method according to claim 29 or claim 30 wherein the further conductive 31. element on the second surface of the substrate is provided for making an off-chip connection to the conductive via.
  - A method according to any one of claims 22 to 31 wherein the photo-32. detectors are photodiodes.
  - A method according to claim 32 wherein the active areas on the first surface of the substrate are anodes.



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- 34. A method according to any one of claims 22 to 33 wherein the cathodes of the photo-detectors are formed as a layer on the second surface of the substrate.
- 35. A method according to any one of claims 22 to 34 wherein the photodetectors are photodiodes of a medical imaging system.
- 5 36. A method according to claim 35 wherein the medical imaging system is a computed tomography system.
  - 37. A method according to any one of claims 22 to 36 wherein the array of photodetectors is provided as a plurality of sub-arrays of photo-detectors.
- 38. A method according to any one of claims 22 to 37 wherein the vias are adjacent to the respective photo-detectors.
  - 39. A radiation detector including photo-detectors formed in at least one substrate according to any one of claims 1 to 17.